Major strengths

- Biocompatible USP Class VI
- No absorption
- Shelf life of 2 years
- Optically clear
- Low fluorescence
- Low water vapor evaporation

A device adapted for Softlithography applications

- Easily molding and bonding, the Flexdym enables a quick prototyping process
- Using common industrial techniques (hot embossing process), Flexdym is easily transferable from research to development
- Thin, cheap, permeable to gas and not to liquid,... The Flexdym appears as the best candidate for next organ on a chip devices

Safety & Protection

• Complete biocompatible component. No gloves or safety equipment required to handle it

Warranty

Warranty I year





















